

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L1	304	(257/428).CCLS.	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 12:11
2	IS&R	L2	853	(257/659).CCLS.	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 12:58
3	IS&R	L7	281	(257/660).CCLS.	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 13:49

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	4241	bare adj chip	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:49
2	BRS	L2	748421	(integrated adj circuit) or IC	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:49
3	BRS	L3	237538	(back adj surface) or (back adj side)	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:49
4	BRS	L4	1933	magnetic adj loss	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:49
5	BRS	L5	196283 4	substrate or wafer	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:49

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L6	654	(bare adj chip) near4 ((integrated adj circuit) or IC)	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:49
7	BRS	L8	1	((bare adj chip) near4 ((integrated adj circuit) or IC)) same (magnetic adj loss)	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:49
8	BRS	L9	1	((bare adj chip) near4 ((integrated adj circuit) or IC)) and (magnetic adj loss)	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:49
9	BRS	L10	125219 7	magnetic	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:49
10	BRS	L12	91862	magnetic near4 (fe or co or ni or f or n or o or cobalt or nickle or iron or fluorine or nitrogen or oxygen)	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:49

	Type	L #	Hits	Search Text	DBs	Time Stamp
11	BRS	L13	1	(bare adj chip) near8 (magnetic near4 (fe or co or ni or f or n or o or cobalt or nickle or iron or fluorine or nitrogen or oxygen))	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:49
12	BRS	L15	1581758	(integrated adj circuit) or IC or chip or die or dice	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:50
13	BRS	L16	49153	magnetic same ((integrated adj circuit) or IC or chip or die or dice)	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:50
14	BRS	L17	1394	(magnetic near4 (fe or co or ni or f or n or o or cobalt or nickle or iron or fluorine or nitrogen or oxygen)) same ((integrated adj circuit) or IC or chip or die or dice)	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:50
15	BRS	L18	0	((magnetic near4 (fe or co or ni or f or n or o or cobalt or nickle or iron or fluorine or nitrogen or oxygen)) same ((integrated adj circuit) or IC or chip or die or dice)) same (substrate or wafer)) same ((back adj surface) or (back adj side))	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:50

	Type	L #	Hits	Search Text	DBs	Time Stamp
16	BRS	L21	1773	((integrated adj circuit) or IC) near8 ((back adj surface) or (back adj side))	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:50
17	BRS	L22	0	((integrated adj circuit) or IC) near8 ((back adj surface) or (back adj side))) near8 (magnetic near4 (fe or co or ni or f or n or o or cobalt or nickle or iron or fluorine or nitrogen or oxygen))	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:50
18	BRS	L23	0	((integrated adj circuit) or IC) near8 ((back adj surface) or (back adj side))) near16 (magnetic near4 (fe or co or ni or f or n or o or cobalt or nickle or iron or fluorine or nitrogen or oxygen))	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:50
19	BRS	L28	2329	magnetic near4 ((back adj surface) or (back adj side))	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:51
20	BRS	L29	246	(magnetic near4 ((back adj surface) or (back adj side))) near8 (substrate or wafer)	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:51

	Type	L #	Hits	Search Text	DBs	Time Stamp
21	BRS	L31	0	fe72allol7	USPAT; US-PG PUB; EPO; JPO; DERVENT; IBM_T DB	2004/05/25 08:51
22	BRS	L32	26	fealo	USPAT; US-PG PUB; EPO; JPO; DERVENT; IBM_T DB	2004/05/25 08:51
23	BRS	L33	47	magnetic adj loss and semiconductor and die	USPAT; US-PG PUB; EPO; JPO; DERVENT; IBM_T DB	2004/05/25 08:51
24	BRS	L34	12493	tokin.as.	USPAT; US-PG PUB; EPO; JPO; DERVENT; IBM_T DB	2004/05/25 08:51
25	BRS	L35	12	semiconductor adj wafer and magnetic adj loss	USPAT; US-PG PUB; EPO; JPO; DERVENT; IBM_T DB	2004/05/25 08:51

	Type	L #	Hits	Search Text	DBs	Time Stamp
26	BRS	L36	14	semiconductor adj wafer and tokin.as.	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:51
27	BRS	L37	19	3963489.uref.	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:51
28	BRS	L38	43	semiconductor adj die and magnetic adj material	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:51
29	BRS	L7	1	((bare adj chip) near4 ((integrated adj circuit) or IC)) near8 (magnetic adj loss)	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:51
30	BRS	L11	13	((bare adj chip) near4 ((integrated adj circuit) or IC)) near8 magnetic	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:51

	Type	L #	Hits	Search Text	DBs	Time Stamp
31	BRS	L14	2	(bare adj chip) same (magnetic near4 (fe or co or ni or f or n or o or cobalt or nickle or iron or fluorine or nitrogen or oxygen))	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:51
32	BRS	L19	225	((magnetic near4 (fe or co or ni or f or n or o or cobalt or nickle or iron or fluorine or nitrogen or oxygen)) same ((integrated adj circuit) or IC or chip or die or dice)) same (substrate or wafer)	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:51
33	BRS	L20	13	((magnetic near4 (fe or co or ni or f or n or o or cobalt or nickle or iron or fluorine or nitrogen or oxygen)) same ((integrated adj circuit) or IC or chip or die or dice)) same (substrate or wafer) and ((back adj surface) or (back adj side))	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:51
34	BRS	L24	2	((integrated adj circuit) or IC) near8 ((back adj surface) or (back adj side))) same (magnetic near4 (fe or co or ni or f or n or o or cobalt or nickle or iron or fluorine or nitrogen or oxygen))	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:51
35	BRS	L25	40	((back adj surface) or (back adj side)) same (substrate or wafer) same ((integrated adj circuit) or IC) same magnetic	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:51

	Type	L #	Hits	Search Text	DBs	Time Stamp
36	BRS	L26	2	((magnetic adj loss) near4 ((back adj surface) or (back adj side))	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:51
37	BRS	L27	6	((magnetic adj loss) same ((back adj surface) or (back adj side))	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:51
38	BRS	L30	9	((magnetic near4 ((back adj surface) or (back adj side))) near8 (substrate or wafer)) same ((integrated adj circuit) or IC)	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:51
39	IS&R	L40	2	("6653573").PN.	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:51
40	BRS	L41	7	("5435903" "5493074" "5639989" "5738931" "5966294" "5998048" "6208000").PN.	USPAT	2004/05/25 08:51

	Type	L #	Hits	Search Text	DBs	Time Stamp
41	BRS	L42	25	noise adj suppression and tokin.as.	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:56
42	BRS	L43	27601	3 near8 5	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:57
43	BRS	L44	0	43 same 32	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:57
44	BRS	L45	1	43 same (magnetic adj loss)	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:58
45	BRS	L46	1	43 and (M-X-Y or MXY)	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:58

	Type	L #	Hits	Search Text	DBs	Time Stamp
46	BRS	L47	338	granular adj magnetic	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:59
47	BRS	L48	98	47 same 5	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/05/25 08:59